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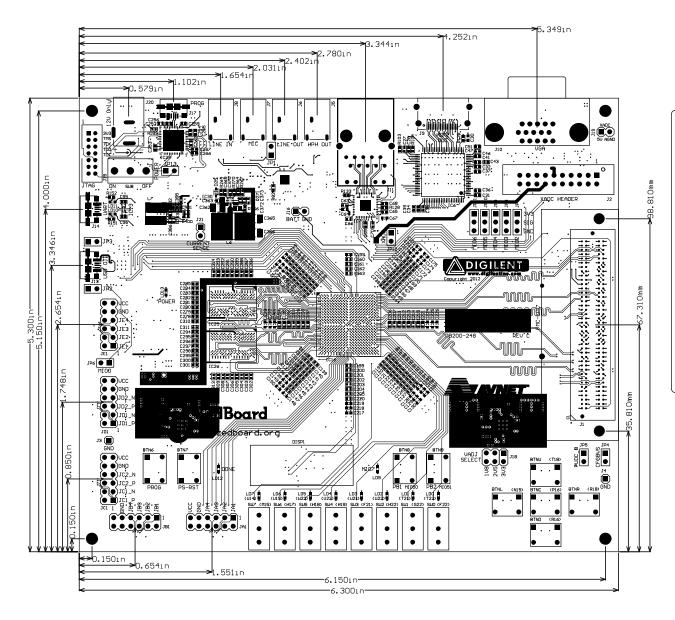
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Layer Stack Up Detail for: ZED.PcbDoc						
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.0102mm	Solder Resist	3.50	
Top Layer	(.GTL)	O. 0356mm	O.1mm	FR-4	4.80	Core
GND2	(.GP1)	0.0356mm	O. Imm	F K-T	7. 80	core
			0.125mm	FR-4	4.80	PrePreg
Mid-Layer 1	(.G1)	O. 017mm	0.125mm	FR-4	4.80	Core
Mid-Layer 2	(.G2)	0.017mm	0.125	18 1	1.00	COLE
			0.125mm	FR-4	4.80	PrePreg
POWER1	(.GP2)	0.0356mm	0.35mm	FR-4	4.80	Core
POWER2	(.GP3)	0.0356mm	0.00			55. 2
			0.125mm	FR-4	4.80	PrePreg
MidLayer3	(.G3)	O. 017mm	0.125mm	FR-4	4.80	Core
Mid-Layer 4	(.G4)	O. 017mm				
		0.0054	0.125mm	FR-4	4.80	PrePreg
GND7	(.GP4)	O. 0356mm	O. 1 mm	FR-4	4.80	Core
Bottom Layer	(.GBL)	0.0356mm				
Bottom Solder Mask	(.GBS)		0.0102mm	Solder Resist	3.50	